BS IEC 62899-503-1:2020

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Printed electronics

Part 503-1: Quality assessment — Test method of displacement current measurement for printed thin-film transistor

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CONTENTS

FOREWORD 3
INTRODUCTION 5
1 Scope 6
2 Normative references 6
3 Terms and definitions 6
4 Abbreviated terms 7
5 Symbols and units 7
6 Measuring method of DCM 8
6.1 Guidelines on measurements of printed TFT channel properties 8
6.2 Procedure for DCM 8
6.2.1 Measuring apparatus 8
6.2.2 Measuring procedure 8
7 Report 10
7.1 Experimental conditions 10
7.2 Appropriate data format 10
Annex A (informative) Experimental results 12
A.1 Charge trapping measurement method 12
A.2 Channel capacitance measurement method 13
Bibliography 15

Figure 1 – Example of structure (left) and schema (right) of a measuring device 8
Figure 2 – Plots of the printed TFT's U_{GS}, I_s, I_D at U_{DS} = −20V with respect to time 9
Figure 3 – Frequency dependence of DCM 10
Figure A.1 – Plot of DCM at U_{DS} = 0 V 13
Figure A.2 – Division of regions according to carrier injection 14

Table 1 – List of symbols 7
Table 2 – Environmental factors 11
Table 3 – Measured properties of the TFT 11
Table A.1 – Obtained trap charge from four cycles (accumulated) 13

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Full document details: BS IEC 62899-503-1:2020

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Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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